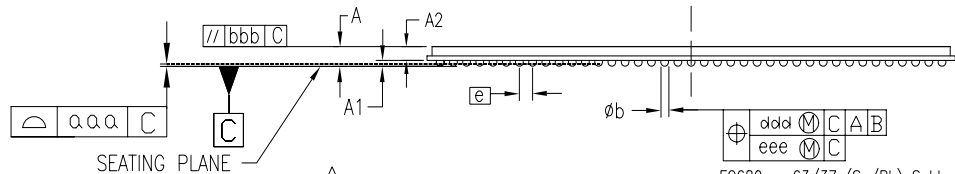
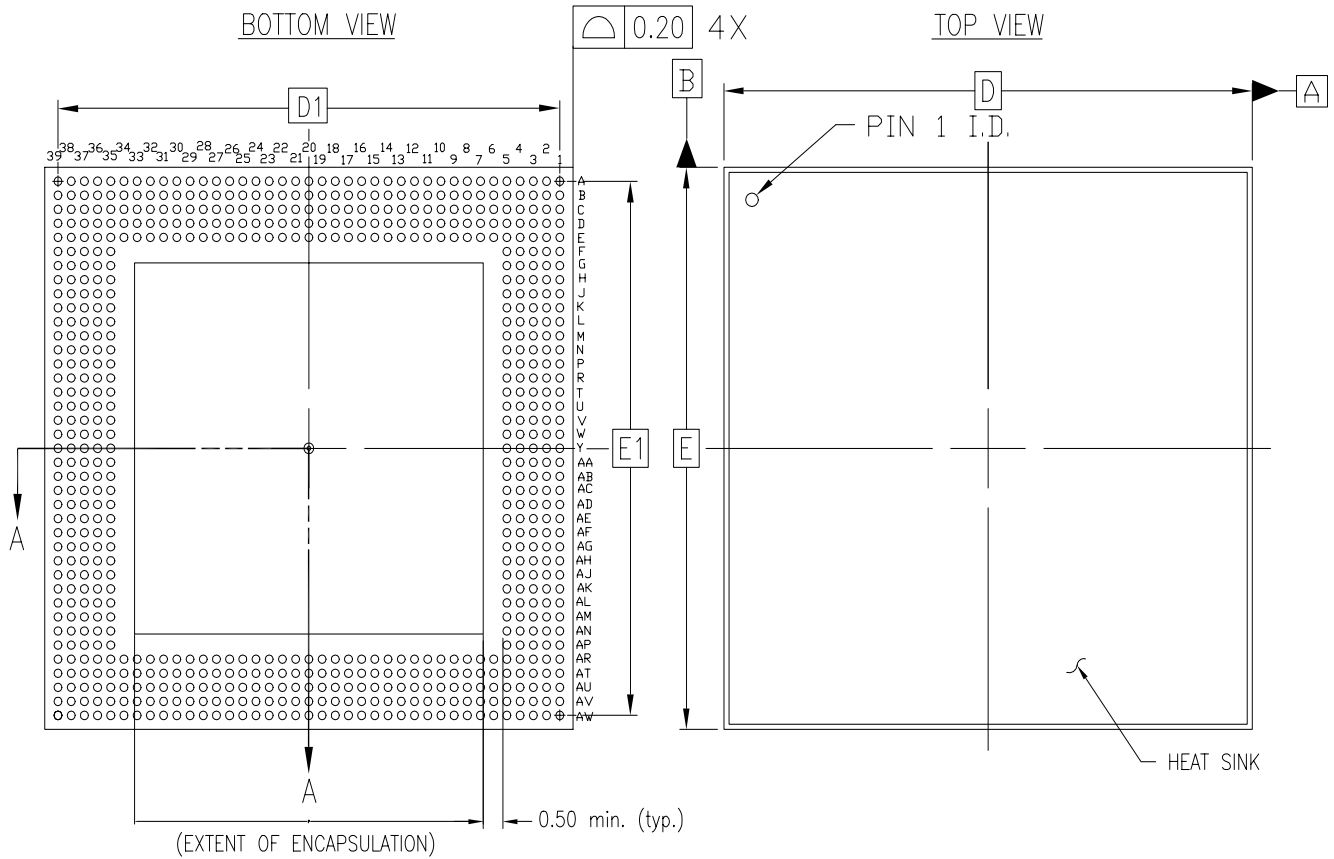


Fine-Pitch Thermally Enhanced BGA (FG680/FGG680) Package



FG680 - 63/37 (Sn/Pb) Solder Balls
 FGG680 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	\sim	1.40	1.70	
A ₁	0.40	0.50	0.60	
A ₂	\sim	\sim	1.10	
A ₃	0.10	\sim	\sim	
D/E	40.00 BASIC			
D ₁ /E ₁	38.00 REF			
e	1.00 BASIC			
ϕb	0.50	0.60	0.70	
aaa	\sim	\sim	0.20	
bbb	\sim	\sim	0.25	
ddd	\sim	\sim	0.25	
eee	\sim	\sim	0.10	
M	39			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
 2. SYMBOL "M" IS THE PIN MATRIX SIZE.
 3. CONFORMS TO JEDEC MO-192-AAU-1 (DEPOPULATED)
- \triangle HEAT SINK PULLBACK - 0.375mm MAX.

SECTION A-A
 (NOT TO SCALE)

680-BALL FINE-PITCH THERMALLY ENHANCED BGA, 1.00MM PITCH (FG680/FGG680)